
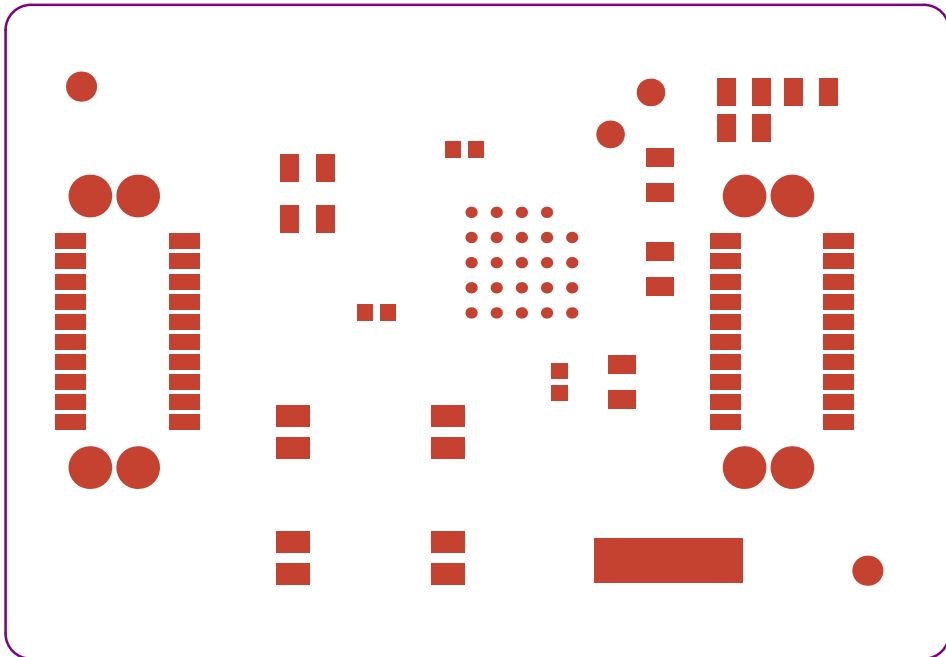

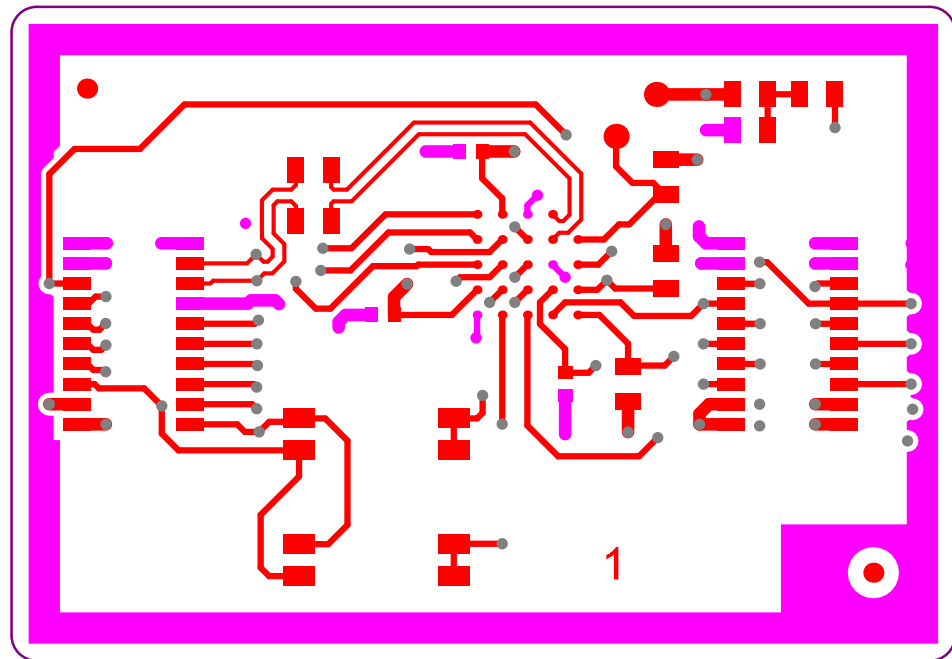



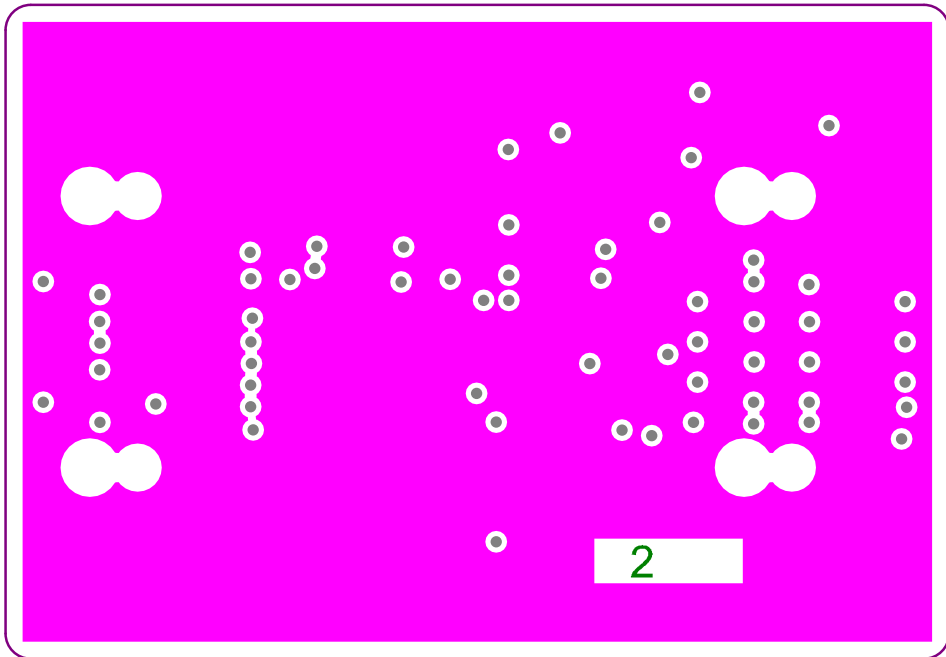
Project: BGA24 OSPI / Hyperbus memory module		
Layer: Top Overlay	Gerber: .GTO	
Variant: [No Variations]	Ref: MB1242	
Date: 2020-FEB-06	Rev: B	




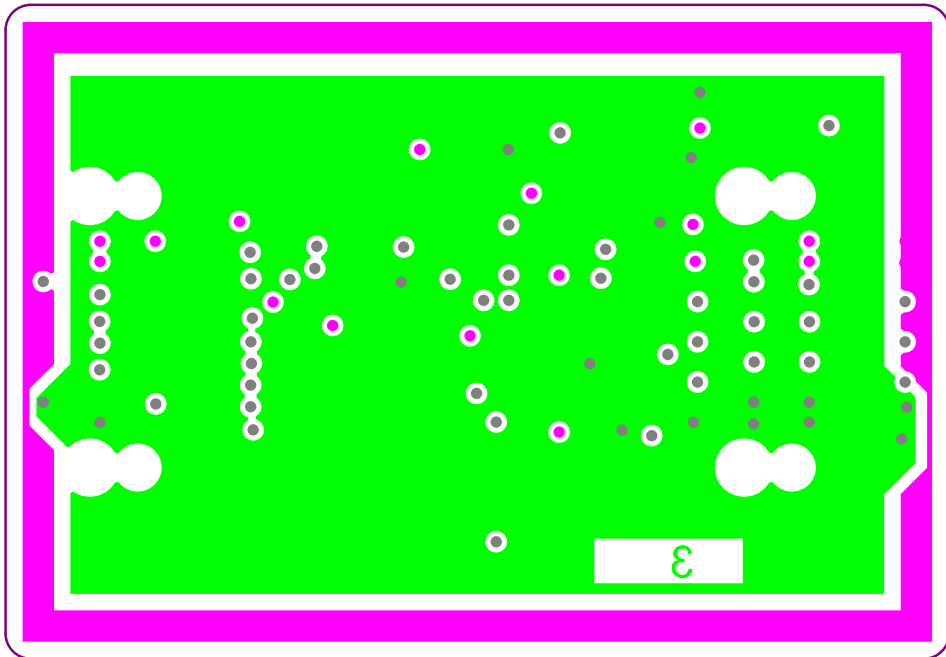
Project: BGA24 OSPI / Hyperbus memory module		
Layer: Top Solder	Gerber: .GTS	
Variant: [No Variations]	Ref: MB1242	
Date: 2020-FEB-06	Rev: B	




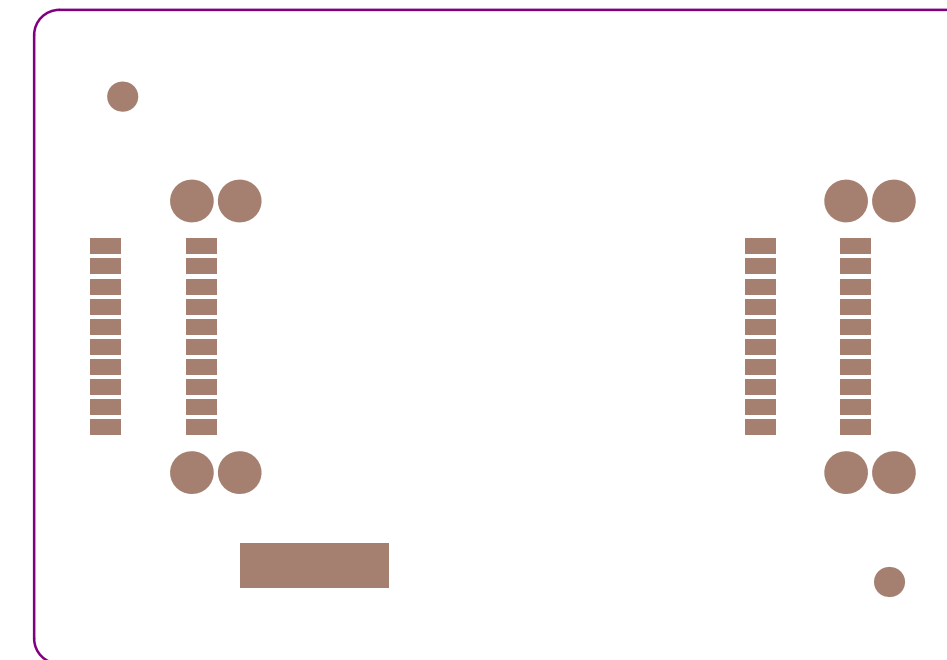
Project: BGA24 OSPI / Hyperbus memory module		
Layer: Top Layer	Gerber: .GTL	
Variant: [No Variations]	Ref: MB1242	
Date: 2020-FEB-06	Rev: B	




Project: BGA24 OSPI / Hyperbus memory module		
Layer: Signal Layer 1	Gerber: .G1	
Variant: [No Variations]	Ref: MB1242	
Date: 2020-FEB-06	Rev: B	



Project: BGA24 OSPI / Hyperbus memory module		
Layer: Signal Layer 2	Gerber: .G2	
Variant: [No Variations]	Ref: MB1242	
Date: 2020-FEB-06	Rev: B	



Project: BGA24 OSPI / Hyperbus memory module		
Layer: Bottom Solder	Gerber: .GBS	
Variant: [No Variations]	Ref: MB1242	
Date: 2020-FEB-06	Rev: B	

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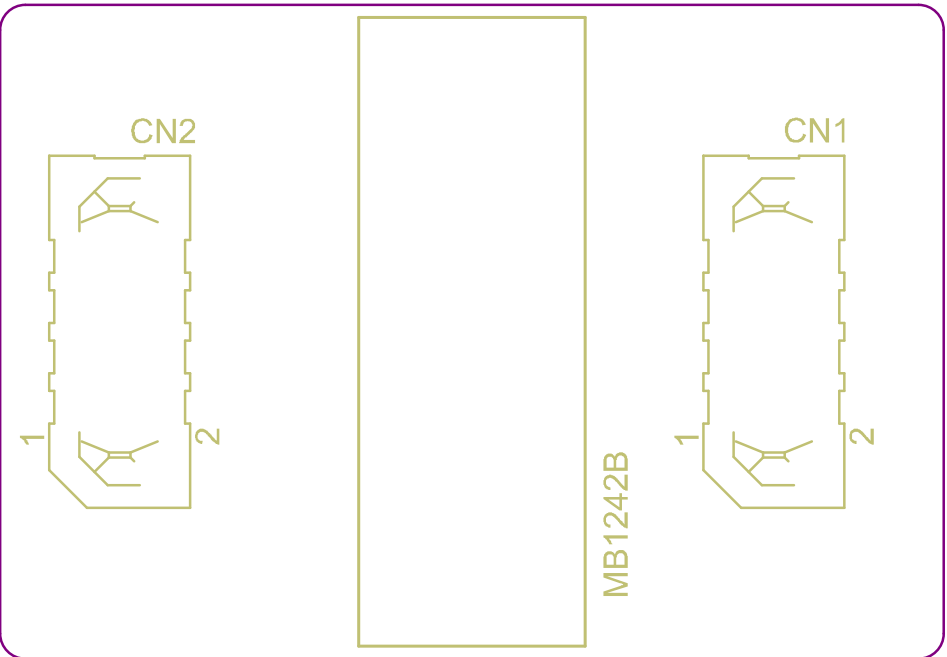
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Project: BGA24 OSPI / Hyperbus memory module		
Layer: Bottom Overlay	Gerber: .GBO	
Variant: [No Variations]	Ref: MB1242	
Date: 2020-FEB-06	Rev: B	

PCB SPECIFICATIONS :

A. MATERIAL :

FR-4

☐ TG-170

☒ TG-150

☐ TG-140

B. MATERIAL FAMILY :

N/A

C. SOLDERMASK COLOR :

☐ GREEN

☐ WHITE

☐ RED

☒ Blue ink PANTONE 2955

D. SILKSCREEN COLOR :

☒ WHITE

☐ YELLOW

☐ BLACK

☐ Blue ink PANTONE 2955

E. SURFACE FINISH :

☒ ENIG

☐ IMMERSION SILVER

☐ IMMERSION TIN

☐ HASL

☐ HASL (PB-FREE)

☐ GOLDEN FINGER

☐ IMPEDANCE CONTROL :

☐ NO

☒ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

G. THROUGH VIA :

PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.

PLUG MATERIAL : ☒ SOLDERMASK ☐ NON-CONDUCTIVE EPOXY.

☐ STACK-UP :

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.

MINIMUM PARAMETERS

DEFAULT

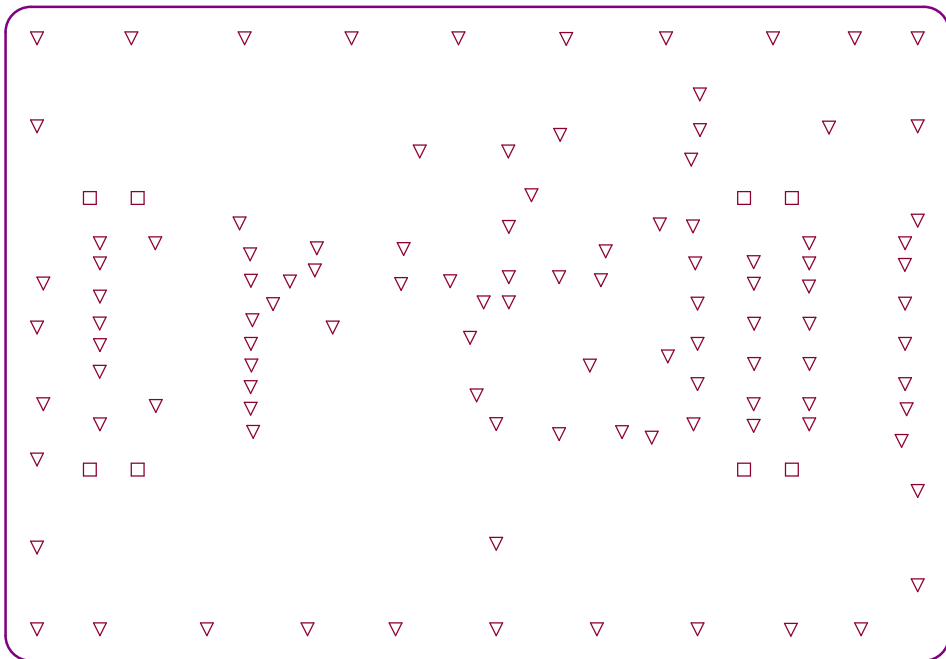
TRACKS : 0.165mm


GAPS : 0.2mm

PCB : TYPE 3

ASPECT-RATIO, AXE Z :
6:1 to 8:1
LEVEL "B"

THE COMPONENTS WITH PLATED THROUGH HOLE (PTH) MAY BE WELDED (CABLED) IN "PIN-IN-PASTE" MODE (IF NECESSARY) ""BOTTOM PASTE""



Project: BGA24 OSPI / Hyperbus memory module		
Layer: Drill Drawing	Gerber: .DRL	
Variant: [No Variations]	Ref: MB1242	
Date: 2020-FEB-06	Rev: B	

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				[Hatched pattern]
2	Top Solder	Solder Resist	0,020mm	3,5	
3	Top Layer	Copper	0,035mm		[Hatched pattern]
4	Dielectric 1	1080HR RC68	0,160mm	4,18	
5	Signal Layer 1	Copper	0,035mm		[Hatched pattern]
6	Dielectric 2	7 x 7628	1,100mm	4,74	
7	Signal Layer 2	Copper	0,035mm		[Hatched pattern]
8	Dielectric 3	1080HR RC68	0,160mm	4,18	
9	Bottom Layer	Copper	0,035mm		[Hatched pattern]
10	Bottom Solder	Solder Resist	0,020mm	3,5	
11	Bottom Overlay				[Hatched pattern]

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape
	8	1,500mm	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded
	107	0,200mm	PTH	Round	Top Layer - Bottom Layer	Via	Rounded
	115 Total						